Technical Data Sheet

SCHULAFORM® 9 C

Acetal (POM) Copolymer
Engineering Plastics

Product Description	
easy flow POM, elevated modulus	

General	
Features	• Good Flow
Processing Method	• Injection Molding
Resin ID (ISO 1043)	• POM

Physical	Nominal Value (English)	Nominal Value (SI)	Test Method
Density	1.41 g/cm³	1.41 g/cm³	ISO 1183/A
Melt Volume-Flow Rate (MVR) (190°C/2.16 kg)	11 cm³/10min	11 cm³/10min	ISO 1133
Mechanical	**Nominal Value (English)**	**Nominal Value (SI)**	**Test Method**
Tensile Modulus	428000 psi	2950 MPa	ISO 527-2/1
Tensile Stress (Yield)	9140 psi	63.0 MPa	ISO 527-2/50
Tensile Strain (Yield)	10 %	10 %	ISO 527-2/50
Hardness	**Nominal Value (English)**	**Nominal Value (SI)**	**Test Method**
Ball Indentation Hardness (H 358/30)	21300 psi	147 MPa	ISO 2039-1
Thermal	**Nominal Value (English)**	**Nominal Value (SI)**	**Test Method**
Heat Deflection Temperature			ISO 75-2/A
264 psi (1.8 MPa), Unannealed	230 °F	110 °C	
Vicat Softening Temperature			
--	324 °F	162 °C	ISO 306/A50
--	295 °F	146 °C	ISO 306/B50
Electrical	**Nominal Value (English)**	**Nominal Value (SI)**	**Test Method**
Surface Resistivity	> 1.0E+15 ohms	> 1.0E+15 ohms	IEC 60093
Volume Resistivity	> 1.0E+13 ohms·m	> 1.0E+13 ohms·m	IEC 62631-3-1
Comparative Tracking Index	600 V	600 V	IEC 60112
Flammability	**Nominal Value (English)**	**Nominal Value (SI)**	**Test Method**
Burning Rate			
0.0787 in (2.00 mm)	2.1 in/min	54 mm/min	ISO 3795
0.0787 in (2.00 mm)	2.1 in/min	54 mm/min	FMVSS 302
Flammability Classification			IEC 60695-11-10, -20
0.06 in (1.5 mm)	HB	HB	
0.12 in (3.0 mm)	HB	HB	
Glow Wire Flammability Index			IEC 60695-2-12
0.06 in (1.5 mm)	1200 °F	650 °C	
0.12 in (3.0 mm)	1160 °F	625 °C	
Glow Wire Ignition Temperature			IEC 60695-2-13
0.06 in (1.5 mm)	1250 °F	675 °C	
0.12 in (3.0 mm)	1200 °F	650 °C	

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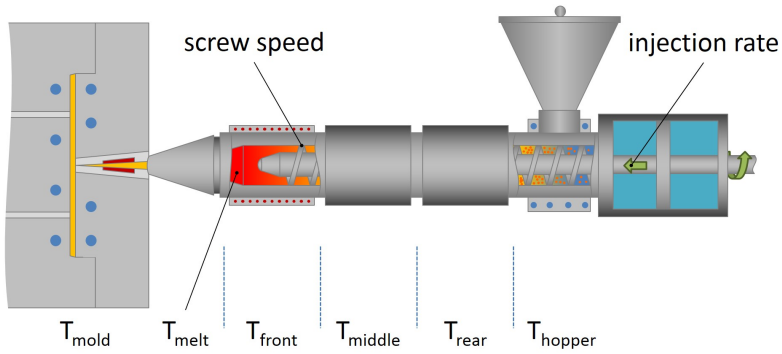

Injection	Nominal Value (English)	Nominal Value (SI)
Drying Temperature	212 °F	100 °C
Drying Time	2.0 to 4.0 hr	2.0 to 4.0 hr
Suggested Max Moisture	0.04 to 0.10 %	0.04 to 0.10 %
Suggested Max Regrind	20 %	20 %
Processing (Melt) Temp	392 to 410 °F	200 to 210 °C
Mold Temperature	140 to 248 °F	60 to 120 °C

Notes

These are typical property values not to be construed as specification limits.